PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chien-Wei Chang	06/05/2009
Ting-Hao Lin	06/05/2009
Ya-Hsiang Chen	06/05/2009
Yu-Te Lu	06/05/2009

RECEIVING PARTY DATA

Name:	Kinsus Interconnect Technology Corp.
Street Address:	No. 1245, Junghua Rd.
Internal Address:	Shin-Wu Shiang
City:	Taoyuan
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12479811

CORRESPONDENCE DATA

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Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

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Correspondent Name: LIN & ASSOCIATES INTELLECTUAL PROPERTY,

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ATTORNEY DOCKET NUMBER: 09174URL

NAME OF SUBMITTER: Jason Z. Lin

Total Attachments: 2

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PATENT REEL: 022790 FRAME: 0382 OF \$40.00 12479811

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PATENT REEL: 022790 FRAME: 0383

ASSIGNMENT

WHEREAS, I/we, Chien-Wei Chang, Ting-Hao Lin, Ya-Hsiang Chen and Yu-Te L								
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful								
improvements in Method For Fabricating Buried Capacitor Structure								
(hereinafter referred to as the Invention) for which an application for United States Letters Patent was								
☐ filed on								
filed as PCT International Application No								
The United States of America;								
Patent number, issue on								
WHEREAS, KINSUS INTERCONNECT TECHNOLOGY CORP.								
whose post office address is No. 1245, Junghua Rd., Shin-Wu Shiang, Taoyuan, Taiwan								
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United States;								
NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I/we, ASSIGNOR,								
by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said invention								
and application throughout the United States of America, including any and all Letters Patent granted on any division,								
continuation, continuation-in-part and reissue of said application.								
ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing,								
prosecution and maintenance of said application or any other patent application(s) in the Unites States for said invention,								
including additional documents that may be required to affirm the rights of ASSIGNEE in and to said invention, all without								
further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and								
communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the invention that are within								
ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may								
be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent								
encompassed within the terms of this instrument, ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's								
heirs, executors, administrators and other legal representatives.								
ALSO, ASSIGNOR hereby authorizes and requests the Director of Patents and Trademarks to issue any and all Letters								
Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for								
ASSIGNEE's sole use and behoof, and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full								
end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by								
ASSIGNOR had this assignment and sale not been made.								
Assignor: Chien-Wei Chang Dated this 5th day of June, at Taiwan								
No. 29, Chang-Ching 5th St., 2009								
Yang-Mei Town,								
Taoyuan Hsien, Taiwan Taiwan								
Signature								
Assignant — Dated this day of								
Assignor. Ting-Hao Lin Date this 5th June, Taiwan 16F, No. 80, Lane 134,								
Sec. 3, Hsin-Yi Road,								
Taipei, Taiwan								
Assignor: Ya-Hei ang Chen Dated this 5th day of June, at Taiwan								
Ambiguot. 14 Historia Onicii								
No. 6, Chung-Hsing Street, 2009 Nan-Yang Village,								
Lun-Pei Country,								
Yun-Lin Hsien,								
Taiwan Signature								

SOLE/JOINT-U.S. ONLY

ASSIGNMENT (SUPPLEMENTAL SHEET) PAGE 2

Title: Method For Fabricating Burie	ed Capaci	itor S <u>tru</u> c	cture		
Inventors: Chien-Wei Chang, Ting-Ha	ao Lin, Y	Ya-Hsiang	Chen and	Yu-Te Lu	
Assignor: Yu-Te Lu No. 93, Hsin Chuang Tzu, Hsin-Chuang Village,	Dated this	5th day of	June, 2009	at Taiwan	
Lu-Chu Country, Taoyuan Hsien, Taiwan		n Yu	Te.		
			Signature		
Assignor:	Dated this	day of		at	
				<u> </u>	
Signature					

RECORDED: 06/07/2009

PATENT REEL: 022790 FRAME: 0385